

# **CD74HC195**

Data sheet acquired from Harris Semiconductor SCHS165

September 1997

# High Speed CMOS Logic 4-Bit Parallel Access Register

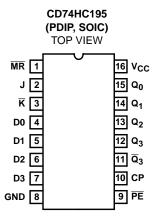
#### Features

- Asynchronous Master Reset
- J, K, (D) Inputs to First Stage
- Fully Synchronous Serial or Parallel Data Transfer
- · Shift Right and Parallel Load Capability
- Complementary Output From Last Stage
- · Buffered Inputs
- Typical  $f_{MAX} = 50MHz$  at  $V_{CC} = 5V$ ,  $C_L = 15pF$ ,  $T_A = 25^{\circ}C$
- Fanout (Over Temperature Range)

  - Bus Driver Outputs ........... 15 LSTTL Loads
- Wide Operating Temperature Range ...-55°C to 125°C
- Balanced Propagation Delay and Transition Times
- Significant Power Reduction Compared to LSTTL Logic ICs
- HC Types

**PInout** 

- 2V to 6V Operation
- High Noise Immunity:  $N_{IL}$  = 30%,  $N_{IH}$  = 30%of  $V_{CC}$  at  $V_{CC}$  = 5V



#### Description

The device is useful in a wide variety of shifting, counting and storage applications. It performs serial, parallel, serial to parallel, or parallel to serial data transfers at very high speeds.

The two modes of operation, shift right (Q $_0$ -Q $_1$ ) and parallel load, are controlled by the state of the Parallel Enable ( $\overline{PE}$ ) input. Serial data enters the first flip-flop (Q $_0$ ) via the J and  $\overline{K}$  inputs when the  $\overline{PE}$  input is high, and is shifted one bit in the direction Q $_0$ -Q $_1$ -Q $_2$ -Q $_3$  following each Low to High clock transition. The J and K inputs provide the flexibility of the JK-type input for special applications and by tying the two pins together, the simple D-type input for general applications. The device appears as four common-clocked D flip-flops when the  $\overline{PE}$  input is Low. After the Low to High clock transition, data on the parallel inputs (D0-D3) is transferred to the respective Q $_0$ -Q $_3$  outputs. Shift left operation (Q $_3$ -Q $_2$ ) can be achieved by tying the Q $_n$  outputs to the Dn-1 inputs and holding the  $\overline{PE}$  input low.

All parallel and serial data transfers are synchronous, occurring after each Low to High clock transition. The CD74HC195 series utilizes edge triggering; therefore, there is no restriction on the activity of the J,  $\overline{K}$ , Pn and  $\overline{PE}$  inputs for logic operations, other than set-up and hold time requirements. A Low on the asynchronous Master Reset  $(\overline{MR})$  input sets all Q outputs Low, independent of any other input condition.

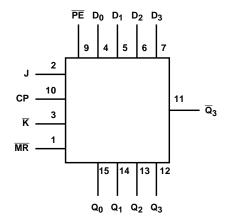
# **Ordering Information**

PART NUMBER	TEMP. RANGE (°C)	PACKAGE	PKG. NO.
CD74HC195E	-55 to 125	16 Ld PDIP	E16.3
CD74HC195M	-55 to 125	16 Ld SOIC	M16.15

#### NOTES:

- 1. When ordering, use the entire part number.
- Die for this part number is available which meets all electrical specifications. Please contact your local sales office or Harris customer service for ordering information.

# Functional Diagram



#### **TRUTH TABLE**

	INPUTS						ОИТРИТ					
OPERATING MODES	MR	СР	PE	J	K	Dn	$Q_0$	Q <sub>1</sub>	Q <sub>2</sub>	Q <sub>3</sub>	$\overline{Q}_3$	
Asynchronous Reset	L	Х	Х	Х	Х	Х	L	L	L	L	Н	
Shift, Set First Stage	Н	1	h	h	h	Х	Н	q <sub>0</sub>	<b>q</b> 1	q <sub>2</sub>	$\bar{q}_2$	
Shift, Reset First Stage	Н	1	h	I	I	Х	L	q <sub>0</sub>	<b>q</b> 1	q <sub>2</sub>	$\bar{q}_2$	
Shift, Toggle First Stage	Н	1	h	h	I	Х	$\bar{q}_0$	q <sub>0</sub>	<b>q</b> 1	q <sub>2</sub>	$\bar{q}_2$	
Shift, Retain First Stage	Н	1	h	I	h	Х	q <sub>0</sub>	q <sub>0</sub>	<b>q</b> 1	q <sub>2</sub>	$\bar{q}_2$	
Parallel Load	Н	1	I	Х	Х	dn	d <sub>0</sub>	d <sub>1</sub>	d <sub>2</sub>	d3	d2	

NOTE: H = High Voltage Level

L = Low Voltage Level,

X = Don't Care

↑ = Transition from Low to High Level

I = Low Voltage Level One Set-up Time Prior to the Low to High Clock Transition

h = Low Voltage Level One Set-up Time prior to the High to Low Clock Transition,

 $dn (q_n)$  = Lower Case Letters Indicate the State of the Referenced Input (or output) One Set-up Time Prior to the Low to High Clock Transition.

#### CD74HC195

#### **Absolute Maximum Ratings**

DC Supply Voltage, V <sub>CC</sub> 0.5V to 7V
DC Input Diode Current, I <sub>IK</sub>
For $V_I < -0.5V$ or $V_I > V_{CC} + 0.5V$ ±20mA
DC Output Diode Current, I <sub>OK</sub>
For $V_O < -0.5V$ or $V_O > V_{CC} + 0.5V$ ±20mA
DC Output Source or Sink Current per Output Pin, IO
For $V_O > -0.5V$ or $V_O < V_{CC} + 0.5V$
DC V <sub>CC</sub> or Ground Current, I <sub>CC or</sub> I <sub>GND</sub>

#### **Thermal Information**

Thermal Resistance (Typical, Note 3)	$\theta_{JA}$ (oC/W)
PDIP Package	90
SOIC Package	190
Maximum Junction Temperature	150 <sup>0</sup> C
Maximum Storage Temperature Range	65°C to 150°C
Maximum Lead Temperature (Soldering 10s)	300 <sup>0</sup> C
(SOIC - Lead Tips Only)	

### **Operating Conditions**

Temperature Range (T <sub>A</sub> )55°C to 125°C
Supply Voltage Range, V <sub>CC</sub>
HC Types2V to 6V
HCT Types
DC Input or Output Voltage, V <sub>I</sub> , V <sub>O</sub> 0V to V <sub>CC</sub>
Input Rise and Fall Time
2V
4.5V 500ns (Max)
6V

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

#### NOTE:

3.  $\theta_{\mbox{\scriptsize JA}}$  is measured with the component mounted on an evaluation PC board in free air.

### **DC Electrical Specifications**

		TES CONDI				25°C		-40°C T	O 85°C	-55°C T	O 125°C	
PARAMETER	SYMBOL	V <sub>I</sub> (V)	I <sub>O</sub> (mA)	V <sub>CC</sub> (V)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNITS
High Level Input	V <sub>IH</sub>	-	-	2	1.5	-	-	1.5	-	1.5	-	V
Voltage				4.5	3.15	•	-	3.15	•	3.15	-	V
				6	4.2	•	-	4.2	-	4.2	-	V
Low Level Input	V <sub>IL</sub>	-	-	2	-	•	0.5	-	0.5	-	0.5	V
Voltage				4.5	-	-	1.35	-	1.35	-	1.35	V
				6	-	-	1.8	-	1.8	-	1.8	V
High Level Output	V <sub>OH</sub>	V <sub>IH</sub> or V <sub>IL</sub>	-0.02	2	1.9	-	-	1.9	-	1.9	-	V
Voltage CMOS Loads			-0.02	4.5	4.4	-	-	4.4	-	4.4	-	V
omeo Loado			-0.02	6	5.9	-	-	5.9	-	5.9	-	V
High Level Output			-	-	-	-	-	-	-	-	-	V
Voltage TTL Loads			-4	4.5	3.98	-	-	3.84	-	3.7	-	V
112 20000			-5.2	6	5.48	-	-	5.34	-	5.2	-	V
Low Level Output	V <sub>OL</sub>	V <sub>IH</sub> or V <sub>IL</sub>	0.02	2	-	-	0.1	-	0.1	-	0.1	V
Voltage CMOS Loads			0.02	4.5	-	-	0.1	-	0.1	-	0.1	V
omeo Loado			0.02	6	-	-	0.1	-	0.1	-	0.1	V
Low Level Output			-	-	-	-	-	-	-	-	-	V
Voltage TTL Loads			4	4.5	-	-	0.26	-	0.33	-	0.4	V
112 2000			5.2	6	-	-	0.26	-	0.33	-	0.4	V
Input Leakage Current	II	V <sub>CC</sub> or GND	-	6	-	1	±0.1	-	±1		±1	μΑ
Quiescent Device Current (Note)	Icc	V <sub>CC</sub> or GND	0	6	į	-	8	-	80	-	160	μΑ

NOTE: For dual-supply systems theorectical worst case ( $V_1 = 2.4V$ ,  $V_{CC} = 5.5V$ ) specification is 1.8mA.

### CD74HC195

# **Prerequisite For Switching Function**

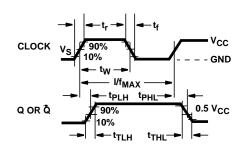
		TEST		25	25°C		O 85°C	-55°C TO 125°C		
PARAMETER	SYMBOL	CONDITIONS	V <sub>CC</sub> (V)	MIN	MAX	MIN	MAX	MIN	MAX	UNITS
Clock Frequency	f <sub>MAX</sub>	-	2	6	-	5	-	4	-	MHz
			4.5	30	-	25	-	20	-	MHz
			6	35	-	29	-	23	-	MHz
MR Pulse Width	t <sub>w</sub>	-	2	80	-	100	-	120	-	ns
			4.5	16	-	20	-	24	-	ns
			6	14	-	17	-	20	-	ns
Clock Pulse Width	t <sub>w</sub>	-	2	80	-	100	-	120	-	ns
			4.5	16	-	20	-	24	-	ns
			6	14	-	17	-	20	-	ns
Set-up Time	t <sub>SU</sub>	-	2	100	-	125	-	150	-	ns
J, K, PE to Clock			4.5	20	-	25	-	30	-	ns
			6	17	-	21	-	26	-	ns
Hold Time	t <sub>H</sub>	-	2	3	-	3	-	3	-	ns
J, K, PE to Clock			4.5	3	-	3	-	3	-	ns
			6	5	-	3	-	3	-	ns
Removal Time,	t <sub>REM</sub>	-	2	80	-	100	-	120	-	ns
MR to Clock			4.5	16	-	20	-	24	-	ns
			6	14	-	17	-	20	-	ns

# Switching Specifications Input $t_r$ , $t_f = 6 \text{ns}$

		TEST		25	°C	-40°C TO 85°C	-55°C TO 125°C	
PARAMETER	SYMBOL	CONDITIONS	V <sub>CC</sub> (V)	TYP	MAX	MAX	MAX	UNITS
HC TYPES					-			
Propagation Delay, CP to	t <sub>PLH</sub> , t <sub>PHL</sub>	C <sub>L</sub> = 50pF	2	ı	175	220	265	ns
Output			4.5	-	35	44	53	ns
			6	-	30	37	45	ns
Propagation Delay,	t <sub>PLH</sub> , t <sub>PHL</sub>	C <sub>L</sub> = 50pF	2	-	150	190	225	ns
MR toOutput			4.5	-	30	38	45	ns
			6	-	26	33	38	ns
Output Transition Times	t <sub>TLH</sub> , t <sub>THL</sub>	C <sub>L</sub> = 50pF	2	-	75	95	110	ns
(Figure 1)			4.5	-	15	19	22	ns
			6	-	13	16	19	ns
Input Capacitance	C <sub>IN</sub>	-	-	-	10	10	10	pF
CP to Q <sub>n</sub> Propagation Delay	t <sub>PLH</sub> , t <sub>PHL</sub>	C <sub>L</sub> = 15pF	5	14	-	-	-	ns
MR to Q <sub>n</sub>	t <sub>PHL</sub>	C <sub>L</sub> = 15pF	5	13	-	-	-	ns
Maximum Clock Frequency	f <sub>MAX</sub>	C <sub>L</sub> = 15pF	5	50	-	-	-	MHz
Power Dissipation Capacitance (Notes 4, 5)	C <sub>PD</sub>	C <sub>L</sub> = 15pF		45	-	-	-	pF

- 4. C<sub>PD</sub> is used to determine the dynamic power consumption, per flip-flop.
  5. P<sub>D</sub> = V<sub>CC</sub><sup>2</sup> f<sub>i</sub> + ∑ (C<sub>L</sub> V<sub>CC</sub><sup>2</sup> + f<sub>O</sub>) where f<sub>i</sub> = Input Frequency, f<sub>O</sub> = Output Frequency, C<sub>L</sub> = Output Load Capacitance, V<sub>CC</sub> = Supply Voltage.

# Test Circuit and Waveforms



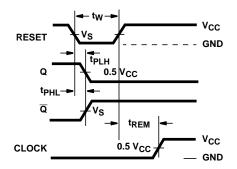


FIGURE 1. CLOCK PRE-REQUISITE AND PROPAGATION DELAYS AND OUTPUT TRANSITION TIMES

FIGURE 2. MASTER RESET PRE-REQUISITE AND PROPAGATION DELAYS

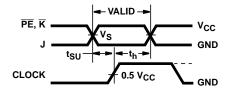


FIGURE 3. J,  $\overline{\mathsf{K}}$  OR PARALLEL ENABLE PRE-REQUISITE TIMES

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